EV Group moves East and West

EV Group formally opened its North American headquarters in Tempe, Arizona. With its Class 10 production cleanroom, the new facility is EV Group's largest installation outside of its worldwide headquarters in Schärding, Austria. It will be used for sales and support services and to conduct joint development work with the Flexible Display Center (FDC), sponsored by Arizona State University (ASU) and the U.S. Army.

The FDC, the result of a $43.7m cooperative agreement between the U.S. Army Research Laboratory and ASU, is working on developing flexible computer screens that can be integrated as part of a soldier's uniform, or rolled up and carried in a soldier's pocket. The agreement has a performance period of five years with an option for an additional $50m over an added five-year period, according to the U.S. Army News Service.

EV Group's North American headquarters will be equipped to provide coating, developing, wafer bonding, nano-imprint lithography, mask aligning, and other technologies. All processes can run up to 150mm wafer sizes, and coating is available for 200mm wafers. Partner Sonix Inc will install a scanning acoustic microscope, for use in wafer bonding analysis.

EV Group will also open a joint cleanroom facility in Korea with its agent Jinsan Scientific Co Ltd and Jinsan Micro-Engineering Ltd (JML). The new facility is located at the Technology Innovation Center of Sung Kyun Kwan University, Suwon, Korea.

JML's lab is designed for MEMS and advanced packaging processes as well as for nanoimprint lithography, and contains a Class 100 cleanroom. EV Group will provide tools for advanced lithography and wafer-bonding processes, including an EVG6200 Infinity mask-and-bond aligner, an EVG520HE semi-automated wafer-bonding and hot-embossing system and an EVG101 spin-and-spray coating system. All systems are capable of processing wafers and substrates up to 200mm. Other equipment suppliers for the cleanroom include Surface Technology Systems plc, Technotrans AG and Raith GmbH.

Corrections to the *Advanced Semiconductors Buyers' Guide* 2004/2005

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Wafer analysis upgraded

Panalytical introduced a series of upgrades for its XRF Wafer Analyzers, which include a new version of the SuperQ software, new boron detection channels, and improved embedded firmware.

The latest SuperQ software offers enhanced FP-Multi results presentation, providing users with a full data report and allowing selection of particular parameters. It also offers an improved interface with complementary techniques, enabling, for example, smooth integration for those fabs that collect data on film thickness by an alternative technology. Data is than transferred to a Panalytical Wafer Analyzer to obtain the film's composition.

New boron detectors improve gauge capability in a BPSG application by at least a factor of two. This can either improve throughput at a given accuracy, or increase accuracy at a given data collection time.

Upgrade options also include new embedded firmware for the PW2820, PW2830 and PW2880 systems. This makes analysis of very thin or flexible wafers highly accurate and reproducible. Improved elimination of external mechanical influences further enhances the quality of results.

For a limited period, owners of PW2800, PW2820, PW2830 and PW2880 systems can upgrade their systems with the new packages at a reduced price. Users should contact their local Panalytical sales representative or request a quotation at:

www.panalytical.com/waferupgrade

GaAs pHEMT supply agreement

Filtronic plc, a designer and manufacturer of customised microwave electronic subsystems and components for the wireless telecommunications and defence industries, and RFIC manufacturer RF Micro Devices Inc (RFMD) have entered into a supply agreement for high volume pHEMT GaAs products.

Manufacture of the products will take place at Filtronic's 6 inch wafer processing facility based in Newton Aycliffe, UK.

RFMD will incorporate Filtronic's pHEMT GaAs products into its own modules aimed at mobile handset and WLAN applications.

Under the terms of the agreement Filtronic has become RFMD's Tier 1 supplier for GaAs pHEMT technology. This means RFMD will use Filtronic as its preferred supplier of pHEMT integrated products for all its requirements.

Filtronic will commence volume production of GaAs pHEMTs for multi throw switches in the second quarter of 2005.

Multi throw switches are used in handsets to enable band/mode switching.